



Reflow Soldering Desktop Systems

The Desktop Series deliver the same high bonding quality as the larger and more automated systems. It offers an ideal price-performance (throughput) ratio. The slide enables easy loading and unloading of the parts directly in front of the operator. If the parts require alignment, this can be done in the front (loading) position where the operator has sufficient free space for loading and alignment of the parts. The position of the camera offers a view that is not blocked by the bonding head. The automatic slide makes improves control when positioning parts positioning compared to manually operated slides. It also enables the operator to spend time on other actions. such as preparing the next parts in between bonding cycles.

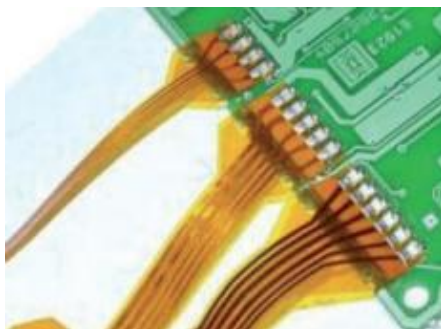
Key Features Reflow Soldering Desktop Systems

- Small and flexible systems for high quality connections
- Ideal price-performance (throughput) ratio
- Simple adjustable frame construction
- For Heat-Seal bonding, Hot Bar Reflow Solderign and Heat Staking
- Reliable process control, by proven technology of Uniflow Power Supply

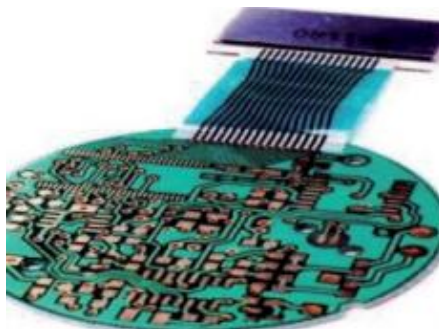
Specifications Reflow Soldering Desktop Systems

Model			
Power requirements	100 to 240 Vac, 50/60 HZ, 16 Amp max		
Air supply	4-8 bar (60-120 psi), dry & filtered air		
Maximum fixture height	50 mm (1.97 inch)		
Gantry open width	520 mm (20.47 inch)		
Fixture assembly baseplate	160 x 160 mm (6.30 x 6.30 inch)		
Starting operation	Two hand control		
Operating temperature	15 - 40 °C		
Operating humidity	93% @ 40 °C		
Bonding head & uniflow technical specifications			
Force range	SH 500:50 - 500 N @ 6 Bar - SH 80:8 - 80 N @ 6 bar		
Hot Bar stroke	SH 500: 50.0 mm - SH 80 : 50.0 mm		
Temperature range Idle	25 to 100 °C	Heat	60 to 600 °C
Temperature range Baseheat	25 to 300 °C	Heat Extended Range	60 to 999 °C
Temperature range Preheat	60 to 300 °C	Postheat	25 to 600 °C
Time period (in 0,1 sec increments) Base Heat	0 to 99.9 seconds	Rise to Heat Time	0 to 9.9 seconds
Time period (in 0,1 sec increments) Rise to preheat time	0 to 9.9 seconds	Heat	0.1 to 99.9 seconds
Time period (in 0.1 Sec increments) preheat	0 to 99.9 seconds or continuous	Postheat	0 to 99.9 seconds
Communications ports	RS-232, RS-485		
WEIGHT & DIMENSIONS	510 x 550 x 600		
Weight (in kg)	40 kg (excluding Uniflow Power Supply)		

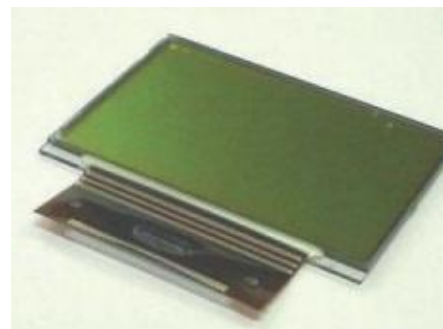
Product applications Reflow Soldering Desktop Systems



Hot Bar reflow soldering



Heat-seal bonding



ACF bonding

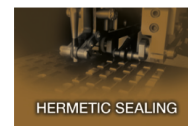


Heat staking

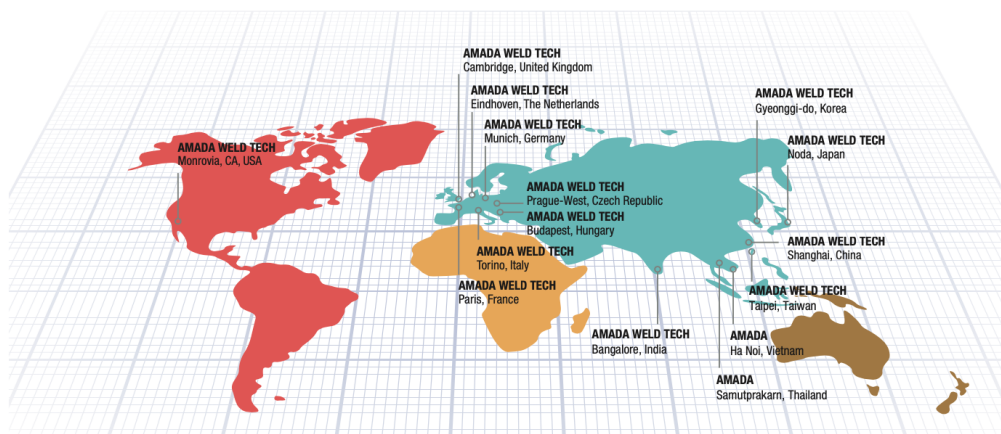
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